

MetalLions

FEATURES

- Winding type realizes small size and low profile
- Prevention of common mode noise at high frequency
- Excellent solderability
- Operating temperature -40~+125 ℃ (Including self temperature rise)
- RoHS Compliant

FEATURES

- Power line noise countermeasure for electronic equipment (Notebook, server applications, Battery, etc.)
- Best for high current circuit such as car
- Wireless charging and power device design

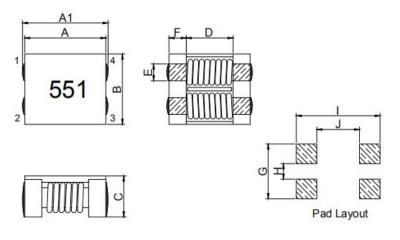
Explanation of Part Number

ACM 1513 F-701 T 80

1 2 3 4 5 6

- 1:Product Series:Wire Wound Chip Common Mode Filters
- ♦ 2:Dimensions:
- 3: Material Code:CF Type
- 4:Common Mode Impedance(Ω)
- 5:Packing(Tape & Reel)
- ♦ 6:Rated Current: 80=8000mA

Shapes and Dimensions [Dimensions in mm]

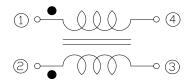


A 1	: 15.6±0.5	mm
B:	13.0±0.5	mm
C:	6.6Max.	mm
D:	9.4 Тур.	mm
E:	2.6 Typ.	mm
F:	2.5 Typ.	mm
G:	9.5 Typ.	mm
H:	3.3 Typ.	mm
l:	16.0 Typ.	mm
J:	8.8 Typ.	mm

A: 15.0±0.5

mm

Equivalent circuit







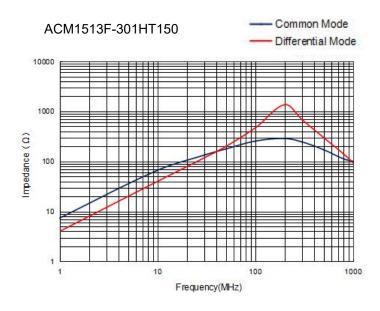
Electrical Characterisitics:

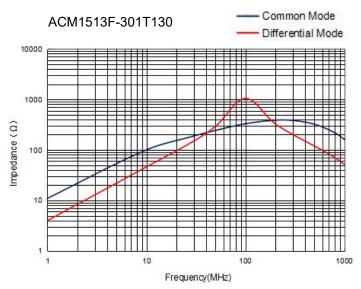
Part Number		100MHz	DC Resistance	Rated Current (A) Max	Rated Voltage (V) Max	Resistance	Marking
	MIN	TYP	(mΩ) Max	(rt) Max	, ,	(MΩ) Min	
ACM1513F-301HT150	225	300	4.0	15.0	80	10	301
ACM1513F-301T130	225	300	5.0	13.0	80	10	301
ACM1513F-551HT120	400	550	5.0	12.0	80	10	551
ACM1513F-551T100	400	550	6.0	10.0	80	10	551
ACM1513F-501T100	400	500	6.0	10.0	80	10	501
ACM1513F-601T100	500	600	7.0	10.0	80	10	601
ACM1513F-701T100	500	700	7.0	10.0	80	10	701
ACM1513F-102T90	800	1000	10.0	9.0	80	10	102
ACM1513F-152T50	1200	1500	23.0	5.0	80	10	152

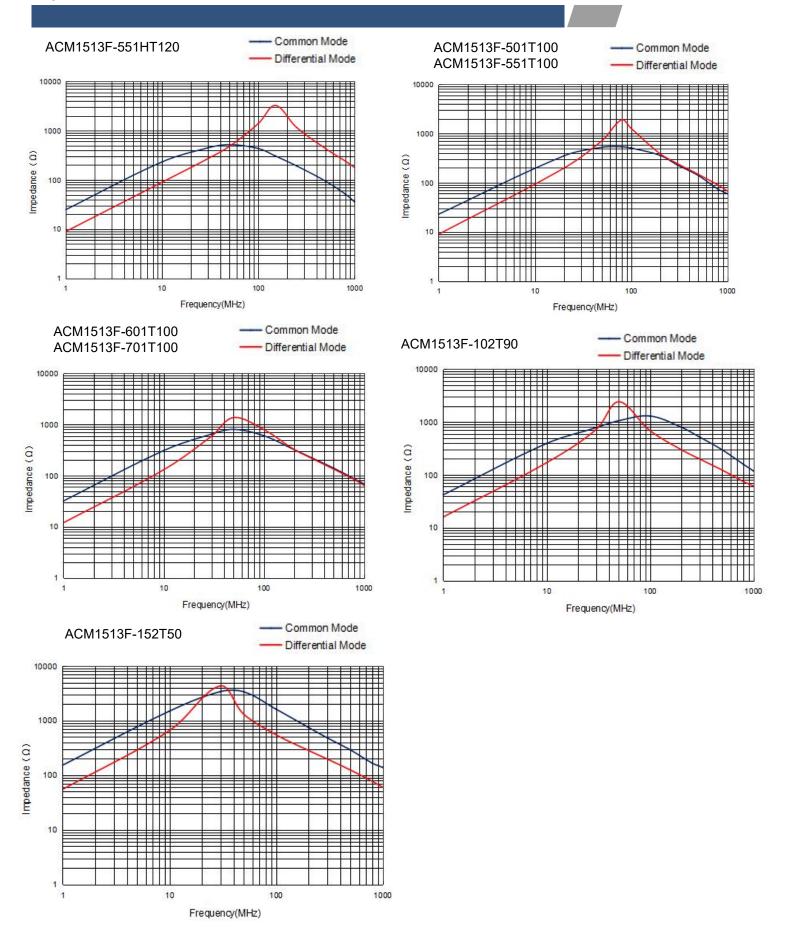
Rated Current: Based on temperature rise ($\triangle T$: 40°C TYP.)

TYPICAL ELECTRICAL CHARACTERISTICS

Impedance VS. Frequency





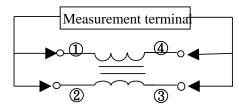




TEST EQUIPMENT

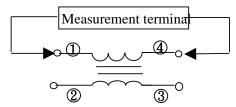
Impedance

Measured by using HP4291B RF Impedance Analyzer.



DC Resistance

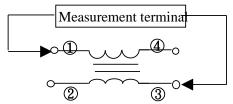
Measured by using Chroma 16502 milliohm meter.



Insulation Resistance

Measured by using Chroma 19073

Measurement voltage: 50v, Measurement time: 60 sec.





Reliability Test

MECHANICAL

TEST ITEM	SPECIFICATION	TEST DETAILS	
Solder ability	The product shall be connected to the test	Apply cream solder to the printed circuit board .	
	circuit board by the fillet (the height is 0.2mm).	Refer to clause 8 for Reflow profile.	
Resistance to	There shall be no damage or problems.	Temperature profile of reflow soldering	
Soldering heat		© 300 — soldering (Peak temperature 260±3°ℂ 10 sec)	
(reflow soldering)		9 g g g g g g g g g g g g g g g g g g g	
		Soldering (Peak temperature 260±3°C 10 sec) 250 Example 200 Pre-heating 150 Slow cooling (Stored at room temperature)	
		g 150 Pre-heating Slow cooling	
		150 ~ 180°C (Stored at room temperature)	
		ο ₅₀ –/	
		2 min 10 2 min. or more	
		k → k → k	
		The specimen shall be passed through the reflow oven with the condition shown in the above profile for 1 time.	
		The specimen shall be stored at standard atmospheric	
		eric conditions for 1 hour, after which the measurement	
		shall be made.	
Terminal strength	The terminal electrode and the ferrite must	Solder a chip to test substrate , and then laterally apply	
	not damaged.	a load 9.8N in the arrow direction.	
		Printed circuit board	
Strength on PC board	The terminal electrode and the ferrite must	Solder a chip to test substrate and then apply a load.	
bending	not damaged.	10 20	
		Test board:FR4 100×40×1mm	
		R10 Fall speed:1mm/sec.	

		45 Dimensions in mm	
	Improduces Within 1999/ - £4h- 1-1/-	After the complex shall be relatived anti-the test start	
High	Impedance:Within±20% of the initial value. Insulation resistance and DC resistance on the	After the samples shall be soldered onto the test circuit	
temperature	specification(refer to clause 2-1) shall be met.	board,the test shall be done. Measurement : After placing for 24 hours min.	
resistance	The terminal electrode and the ferrite must not	Temperature: +125±2°C	
	damaged.	Applied voltage : Rated voltage	
		Applied current : Rated current	
		Testing time : 500±12 hours	
		<u> </u>	

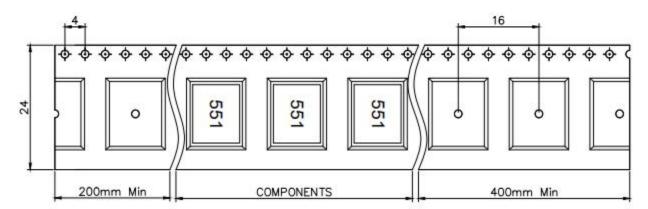


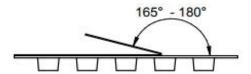
MECHANICAL

TEST ITEM	SPECIFICATION	TEST DETAILS
Humidity	Impedance:Within±20% of the initial value.	After the samples shall be soldered onto the test circuit
resistance	Insulation resistance and DC resistance on the	board,the test shall be done.
	specification(refer to clause 2-1) shall be met.	Measurement : After placing for 24 hours min.
	The terminal electrode and the ferrite must not	Temperature : +60±2℃ , Humidity : 90 to 95 %RH
	damaged.	Applied voltage : Rated voltage
		Applied current : Rated current
		Testing time : 500±12 hours
Thermal shock	Impedance:Within±20% of the initial value. Insulation resistance and DC resistance on the specification(refer to clause 2-1) shall be met. The terminal electrode and the ferrite must not damaged.	1 cycle 30 min 30 sec 30 min.
Low	Impedance:Within±20% of the initial value.	After the samples shall be soldered onto the test
temperature	Insulation resistance and DC resistance on the	circuit board,the test shall be done.
storage	specification(refer to clause 2-1) shall be met.	Measurement : After placing for 24 hours min.
_	The terminal electrode and the ferrite must	Temperature : -40±2℃
	not damaged.	Testing time : 500±12 hours
Vibration	Impedance:Within±20% of the initial value.	After the samples shall be soldered onto the test circuit
	Insulation resistance and DC resistance on	board,the test shall be done.
	the specification(refer to clause 2-1)	Frequency : 10 to 55 Hz
	shall be met.	Amplitude : 1.52 mm
	The terminal electrode and the ferrite must	Dimension and times : X ,Y and Z directions
	not damaged.	for 2 hours each.
Solderability	New solder More than 75%	Flux (rosin, isopropyl alcohol{JIS-K-1522}) shall be coated
		over the whole of the sample before hard, the sample shall
		then be preheated for about 2 minutes in a temperature
		of 130∼150℃ and after it has been immersed to a depth
		0.5mm below for 3±0.2 seconds fully in molten solder
		M705 with a temperature of 245±2℃. More than 75% of the
		electrode sections shall be couered
		with new solder smoothly when the sample is taken out
		of the solder bath.



Packaging





Tape width	Distance	Pull-of force
24 mm	16 mm	10~120g

Packing Quantity

350 pcs./reel